

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A digital micro-mirror device (DMD) package, comprising:
 - a base substrate having a top surface and a bottom surface;
 - ~~a metallic adhesive disposed on the top surface of the base substrate;~~
 - ~~a semiconductor chip having a metallic layer formed on a back surface of the chip, the semiconductor chip attached to the top surface of the base substrate with a metallic adhesive adhering to the metallic layer overlying the metallic adhesive and electrically connected with the base substrate;~~
 - ~~a metallic layer disposed between the semiconductor chip and the metallic adhesive;~~
 - ~~one or more mirrors mounted on the semiconductor chip; and~~
 - ~~a hermetic sealing means covering the semiconductor chip including the one or more mirrors.~~
2. (Original) The DMD package of claim 1, which further comprises a heat sink attached on the bottom surface of the base substrate.
3. (Previously presented) The DMD package of claim 1, wherein the base substrate is selected from the group consisting of a ceramic board, a plastic board, and a printed circuit board.
4. (Previously presented) The DMD package of claim 1, wherein the metallic layer is selected from the group consisting of Va, Au, Ni, Ag, Cu, Al, Pb, Sn, Sb, Pd, and metal-containing compounds thereof.
5. (Previously presented) The DMD package of claim 1, wherein the metallic adhesive is solder.
6. (New) A digital micro-mirror device (DMD) package, comprising:
 - a base substrate;
 - a semiconductor chip; and
 - an adhesive adhering a back surface of the semiconductor chip to the base substrate,

wherein the semiconductor chip includes a metallic layer formed on the back surface of the semiconductor chip and the adhesive adhered to the metallic layer.

7. (New) The DMD package of claim 6 wherein the adhesive is an adhesive that is solidified at room temperature.

8. (New) The DMD package of claim 6 wherein the adhesive is solder.

9. (New) The DMD package of claim 6 wherein the metallic layer is comprised of metal having a low melting point.

10. (New) The DMD package of claim 9 wherein the metallic layer is comprised of a material selected from the group consisting of Va, Au, Ni, Ag, Cu, Al, Pb, Sn, Sb, Pd, and metal-containing compounds thereof.